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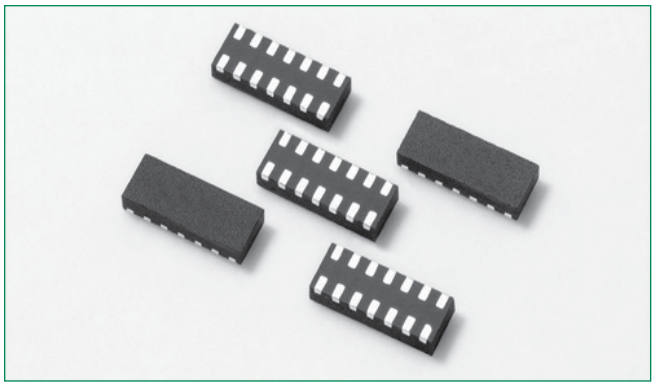
TVS Diode Array (SPA® Diodes)

Low Capacitance ESD Protection - SP3011 Series

SP3011 Series 0.40pF Diode Array for USB 3.0

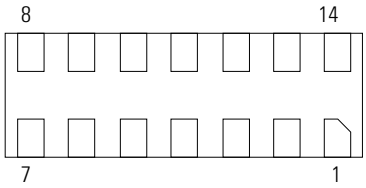
RoHS Pb GREEN



Description

The SP3011 integrates six channels of ultra-low capacitance rail-to-rail diodes and an additional zener diode to provide protection for USB 3.0 ports that may experience destructive electrostatic discharges (ESD). This high density array can safely absorb repetitive ESD strikes at the maximum level specified in the IEC 61000-4-2 international standard (Level 4, ±8kV contact discharge) without performance degradation. It's extremely low loading capacitance makes it ideal for protecting any high-speed signal pins.

Pinout

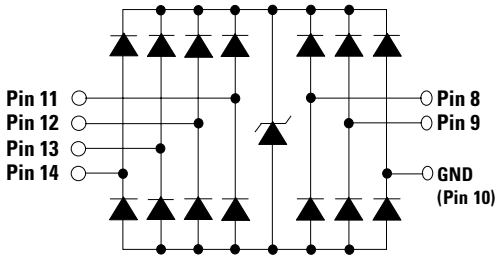


*Pins 1, 2, 3, 4, 5, 6, 7 are not internally connected but should be connected to the opposite pin with the PCB trace.

Features

- ESD, IEC 61000-4-2, ±8kV contact, ±15kV air
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning, IEC 61000-4-5, 3A (8/20μs)
- Low capacitance of 0.4pF (TYP) per I/O
- Low leakage current of 0.1μA (TYP) at 5V
- Small form factor μDFN (JEDEC MO-229) package saves board space
- RoHS compliant and lead-free
- AEC-Q101 qualified

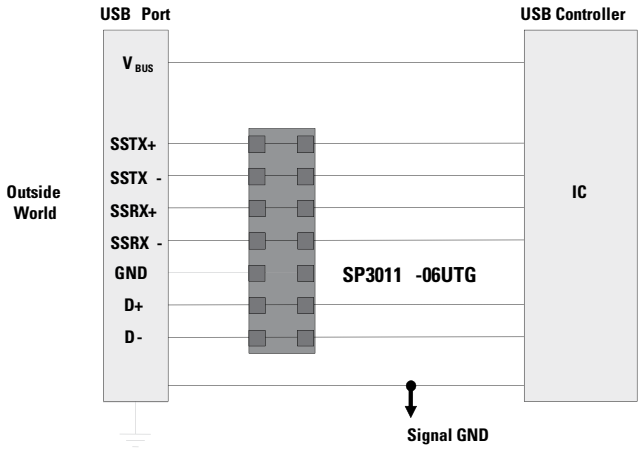
Functional Block Diagram



Applications

- Notebooks
- External Storage
- Digital Camcorder
- MP3/PMP Player
- Desktops
- Ultramobile PC
- Smartphone
- Set Top Box (DVR/PVR)

Application Example



Additional Information

Datasheet | Resources | Samples

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

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Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current (t_p=8/20µs)	3.0	A
T_{OP}	Operating Temperature	–40 to 125	°C
T_{STOR}	Storage Temperature	–55 to 150	°C

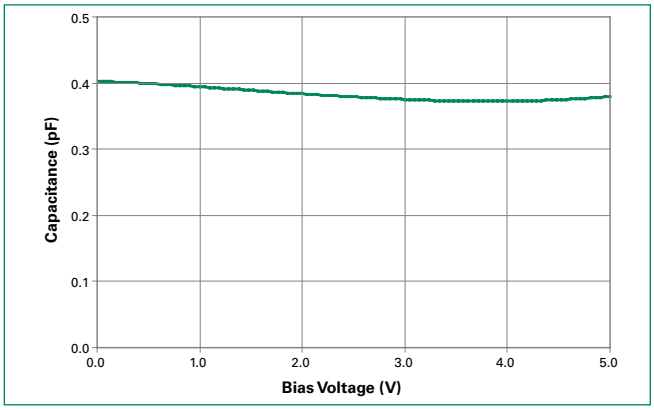
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Characteristics (T_{OP}=25°C)

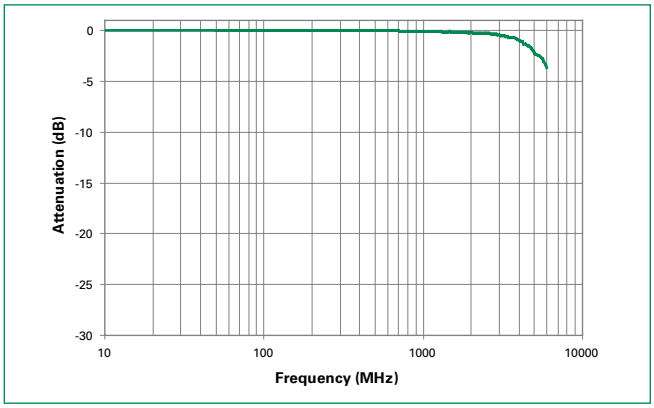
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			6.0	V
Reverse Leakage Current	I_{LEAK}	V_R=5V, Any I/O to GND		0.1	0.5	µA
Clamp Voltage[1]	V_C	I_{PP}=1A, t_p=8/20µs, Fwd		11.0		V
		I_{PP}=2A, t_p=8/20µs, Fwd		12.5		V
Dynamic Resistance	R_{DYN}	$(V_{C2}-V_{C1}) / (I_{PP2}-I_{PP1})$		1.5		Ω
ESD Withstand Voltage[1]	V_{ESD}	IEC61000-4-2 (Contact)	±8			kV
		IEC61000-4-2 (Air)	±15			kV
Diode Capacitance[1]	$C_{I/O-GND}$	Reverse Bias=0V		0.4		pF

Note: [1] Parameter is guaranteed by design and/or device characterization.

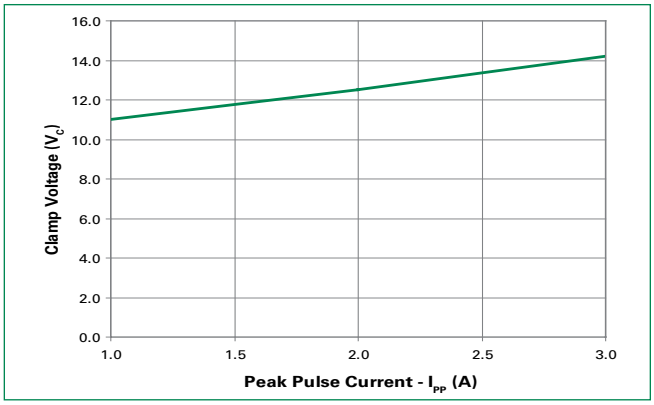
Capacitance vs. Bias Voltage



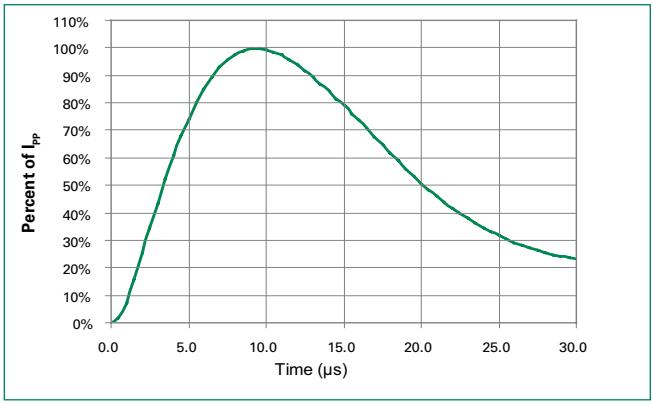
Insertion Loss (S21) I/O to GND



Clamping Voltage vs. I_{PP}



Pulse Waveform



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TVS Diode Array (SPA® Diodes)

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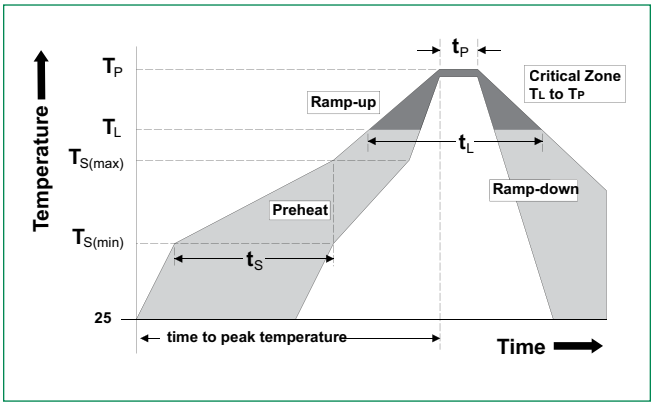
Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	**- Temperature Min ($T_{s(min)}$)**	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	**- Temperature (T_L) (Liquidus)**	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C



Part Numbering System

SP 3011 - 06 U T G

- SP 3011: TVS Diode Arrays (SPA® Diodes) — Series
- 06: **Number of Channels** — -06 = 6 Channels
- U: **Package** — U=µDFN-14 (3.5x1.35mm)
- T: T= Tape & Reel
- G: G= Green

Product Characteristics

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :
1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Part Marking System

R * 6

- R: Product Series R = SP3011
- *: Assembly Site
- 6: Number of Channels

Ordering Information

Part Number	Package	Min. Order Qty.
SP3011-06UTG	µDFN-14	3000

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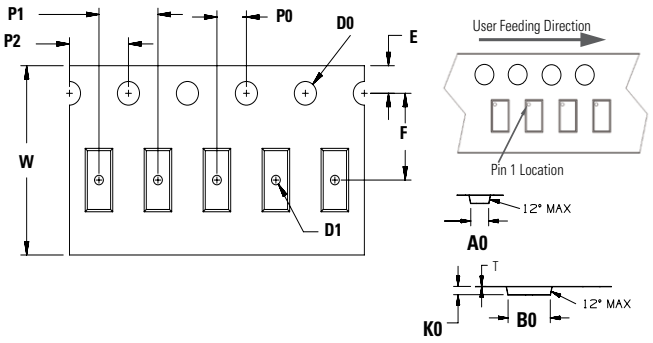
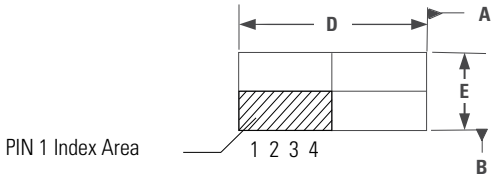
Embossed Carrier Tape & Reel Specification — µDFN-14



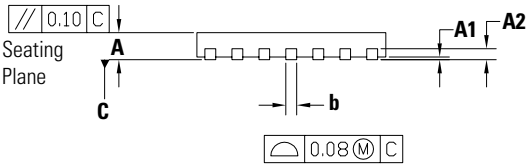
Symbol	Millimeters
A0	1.58 ± 0.10
B0	3.73 ± 0.10
D0	0.60 + 0.05
D1	Ø 0.60 + 0.05
E	1.75 ± 0.10
F	5.50 ± 0.05
K0	0.68 ± 0.10
P0	2.00 ± 0.05
P1	4.00 ± 0.10
P2	4.00 ± 0.10
T	0.28 ± 0.02
W	12.00 + 0.30 /- 0.10

Package Dimensions — µDFN-14 (3.5x1.35x0.5mm)

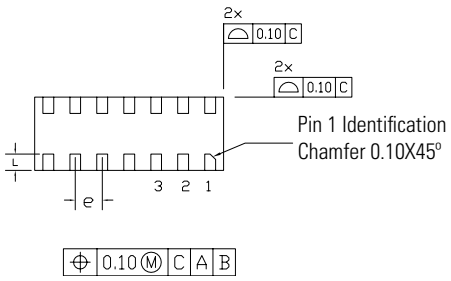
Top View



Side View



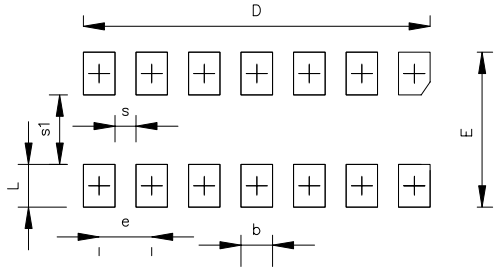
Bottom View



Package	µDFN-14 (3.5x1.35x0.5mm)					
JEDEC	MO-229					
Symbol	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
A2		0.203 Ref			0.008 Ref	
b	0.15	0.20	0.25	0.006	0.008	0.012
D	3.40	3.50	3.60	0.134	0.138	0.142
D2	-	-	-	-	-	-
E	1.25	1.35	1.45	0.050	0.054	0.058
E1	-	-	-	-	-	-
e		0.500 BSC			0.020 BSC	
L	0.25	0.30	0.35	0.010	0.012	0.014

Notes:
1. Dimension and tolerancing comform to ASME Y14.5M-1994.
2. Controlling dimensions: Millimeter. Converted Inch dimensions are not necessarily exact.

Recomended Soldering Pad Layout



Symbol	Millimeter			Inches		
D	3.29	3.30	3.31	0.1295	0.1299	0.1303
E	1.44	1.45	1.46	0.0567	0.0571	0.0575
b	0.29	0.30	0.31	0.0114	0.0118	0.0122
L	0.39	0.40	0.41	0.0154	0.0158	0.0161
e		0.50typ			0.020typ	
s	0.19	0.20	0.21	0.0075	0.0078	0.0083
s1	0.64	0.65	0.66	0.0252	0.0256	0.0260

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